Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**PAD FUNCTION:**

1. **CATHODE**
2. **ANODE**
3. **REFERENCE**

**..028”**

**3**

**1 2**

**.033”**

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size: .004 x .004”**

**Backside Potential: ANODE**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .028” X .033” DATE: 2/2/23**

**MFG: SILICON SUPPLIES THICKNESS .011” P/N: TLV431**

**DG 10.1.2**

#### Rev B, 7/1